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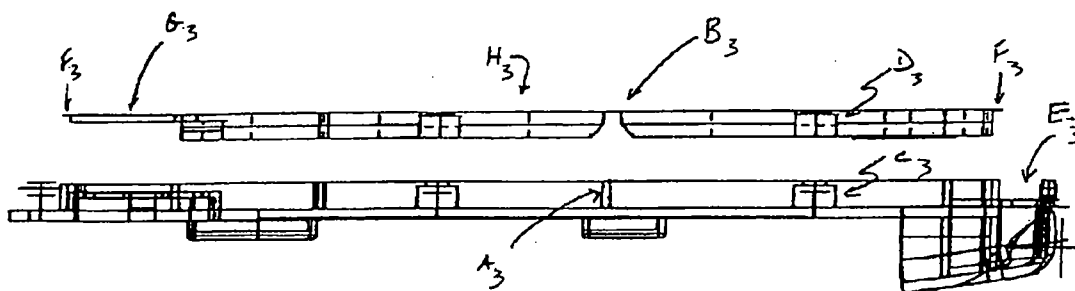
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(54) Title: CONFORMING SHIELDED FORM FOR ELECTRONIC COMPONENT ASSEMBLIES AND METHODS FOR
MAKING AND USING SAME



(57) Abstract: The present invention is directed to electronic components from electromagnetic interference through the use of conforming shield enclosure (A3, A5). Conforming shield enclosures are flexible metalized thermoformed thin-wall polycarbonate polymer film substrates used to shield a radiation source. The present invention relates to conforming shielded forms for electronic component assemblies and specifically to electronic component assemblies, which are shielded, to protect against electromagnetic and radiofrequency interference. Specifically, the shielded electronic component assembly comprises: (a) a semiconductor device within the assembly; (b) a reference potential source; (c) a housing enclosing the semiconductor device within the assembly; and (d) a conforming shield enclosure electrically connected to the reference potential source. The conforming shield enclosure comprises a flexible, metalized thermoformable polymer having dimensions conforming to the housing and enclosing and thereby shielding the semiconductor device from electromagnetic frequencies. The conforming shield enclosure is prepared by paint metalization.

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